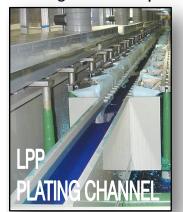
SPOTTER-CS



EESA is introducing the **SPOTTER-CS**, the ultimate selective *spot* plating cell for deposition in continuous motion on cut strip leadframes or loose piece components.

The SPOTTER-CS is used in the "LPP 1/U" range of plating equipment. The L/F cut strips are automaticaly loaded on transporter jigs placed one after the other one on an endless conveyor system. The LPP 1/U equipment is using the same principle as on a Reel-To-Reel plating



line i.e. the chemical solution is brought with a high agitation around the parts in a plating cell channel equiped with shielding screens in the front of the anodes in to improve the thickness distribution. Therefore, the parts can be plated at a higher current density and in continuous motion allowing a constant deposition



The LPP 1/U plating line is using an automatic cassette to cassette loading/unloading system. The transfer of the strips from the jigs to the SPOTTER-CS masking plates (and back to the jigs after "spot" plating) is made by an automatic "pick and place" handling mechanism.







A GUARANTEE FOR SUBSTANTIAL SAVING OF PRECIOUS METAL

ELECTROPLATING ENGINEERING for SELECTIVE APPLICATIONS

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